

KLT-V3MF-IMX214 V2.0

SONY IMX214 MIPI Interface Mise au point fixe 13MP M12 Module de caméra



Module de caméra No.	KLT-V3MF-IMX214 V2.0
Capteur d'image	IMX214
EFL	2.5 mm
F.NO	2.4
Pixel	4228 x 3136
Angle de vue	139°(D) 108°(H) 77°(V)
Type d'objectif	1/3.06 pouce
Dimensions de l'objectif	13.40 x 13.40 x 15.29 mm
Taille du module	190 x 13.40 mm
Type de module	Mise au point fixe
Interface	MIPI

Référence du connecteur d'accouplement. BBR43-30KB533



Connecteur d'accouplement sur la carte principale. Vendu séparément.

[Product Brief]

Ver.1.0

IMX214

Diagonal 5.867mm (Type 1/3.06) 13M Pixel CMOS Image Sensor with Square Pixel for Color Cameras

Description

IMX214 is a diagonal 5.867mm (Type 1/3.06) 13M pixel CMOS active pixel type stacked image sensor with a square pixel array. It adopts Exmor RS™ technology to achieve high speed image capturing by column parallel A/D converter circuits and high sensitivity and low noise image (comparing with conventional CMOS image sensor) through the backside illuminated imaging pixel structure. R, G, and B pigment primary color mosaic filter is employed. By introducing spacially varying exposure technology, high dynamic range still pictures and movies are achievable. It equips an electronic shutter with variable integration time. It operates with three power supply voltages: analog 2.7 V, digital 1.0V and 1.8 V for input/output interface and achieves low power consumption. IMX214 is designed for use in cellular phones or tablet devices*.

Functions and Features

- ◆ Back illuminated and stacked CMOS image sensor Exmor RS
- ◆ Single Frame High Dynamic Range (HDR) with equivalent full pixels.
- ◆ High signal to noise ratio (SNR).
- ◆ Full resolution @30fps (Normal / HDR), 4K2K @30fps (Normal / HDR), 1080p @60fps (Normal / HDR)
- ◆ Output video format of RAW10/8, COMP8/6
- ◆ Pixel binning readout and H/V sub sampling function
- ◆ Advanced Noise Reduction (Chroma noise reduction and luminance noise reduction)
- ◆ Independent flipping and mirroring.
- ◆ CSI 2 serial data output (MIPI 2lane/4lane, Max. 1.2Gbps/lane, DPHY spec. ver. 1.1 compliant)
- ◆ 2wire serial communication
- ◆ Two PLLs for independent clock generation for pixel control and data output interface.
- ◆ Advanced Noise Reduction.
- ◆ Dynamic Defect Pixel Correction.
- ◆ Zero shutter lag.
- ◆ Power on reset function
- ◆ Dual sensor synchronization operation.
- ◆ 8K bit of OTP ROM for users.
- ◆ Built in temperature sensor

NOTE)

1. When using this product for another application, Sony does not guarantee the quality and reliability of product. Therefore, don't use this for applications other than cellular phone and Tablet PCs. Consult your Sony sales representative if you have any questions.

Device Structure

◆ CMOS image sensor	
◆ Image size	: Diagonal 5.867mm (Type 1/3.06)
◆ Total number of pixels	: 4224 (H) × 3200(V) approx. 13.51M pixels
◆ Number of effective pixels	: 4224 (H) × 3136 (V) approx. 13.25 M pixels
◆ Number of active pixels	: 4208 (H) × 3120 (V) approx. 13.13 M pixels
◆ Chip size	: 6.100mm (H) × 4.524mm (V)
◆ Unit cell size	: 1.12 μm (H) × 1.12 μm (V)
◆ Substrate material	: Silicon

Functional Description

System Outline

IMX214 is a CMOS active pixel type image sensor which adopts the Exmor RS™ technology to achieve high sensitivity, low noise and high speed image capturing. It is embedded with backside illuminated imaging pixel, low noise analog amplifier, column parallel A/D converters which enables high speed capturing, digital amplifier, image binning circuit, timing control circuit for imaging size and frame rate, CSI2 image data high speed serial interface, PLL oscillator, and serial communication interface to control these functions.

Several additional image processing functions and peripheral circuits are also included for easy system optimization by the users. A one time programmable memory is embedded in the chip for storing the user data. It has 8 K-bit for users, 10 K-bit as a whole.

Block Diagram



Exmor RS

* Exmor RS is a trademark of Sony Corporation. The Exmor RS is a Sony's CMOS image sensor with high-resolution, high-performance and compact size by replacing a supporting substrate in Exmor R™ which changed fundamental structure of Exmor™ pixel adopted column parallel A/D converter to back-illuminated type, with layered chips formed signal processing circuits.

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Application circuits shown, if any, are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits.